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Suwon-si (KR)**(21) Appl. No.: **17/683,604**(22) Filed: **Mar. 1, 2022**(57) **ABSTRACT**

A method of manufacturing a printed circuit board includes: forming a resist layer; exposing first areas of the resist layer spaced apart from each other; after exposing the first areas, exposing second areas of the resist layer, the second areas being spaces between the first areas; forming first and second openings spaced apart from each other in the first and second areas by developing the resist layer; and forming a plurality of conductor patterns by filling the first and second openings with conductors.

